

LMT84, LMT84-Q1 1.5-V, SC70/TO-92/TO-92S, Analog Temperature Sensors

1 Features

- LMT84-Q1 is AEC-Q100 Qualified for Automotive Applications:
 - Device Temperature Grade 0: -40°C to $+150^{\circ}\text{C}$
 - Device HBM ESD Classification Level 2
 - Device CDM ESD Classification Level C6
- LMT84LPG (TO-92S package) has a Fast Thermal Time Constant, 10-s Typical (1.2 m/s Airflow)
- Very Accurate: $\pm 0.4^{\circ}\text{C}$ Typical
- Low 1.5-V Operation
- Average Sensor Gain of $-5.5\text{ mV}/^{\circ}\text{C}$
- Low $5.4\text{-}\mu\text{A}$ Quiescent Current
- Wide Temperature Range: -50°C to 150°C
- Output is Short-Circuit Protected
- Push-Pull Output With $\pm 50\text{-}\mu\text{A}$ Drive Capability
- Footprint Compatible With the Industry-Standard LM20/19 and LM35 Temperature Sensors
- Cost-Effective Alternative to Thermistors

2 Applications

- Automotive
- Infotainment and Cluster
- Powertrain Systems
- Smoke and Heat Detectors
- Drones
- Appliances

3 Description

The LMT84 and LMT84-Q1 are precision CMOS temperature sensors with $\pm 0.4^{\circ}\text{C}$ typical accuracy ($\pm 2.7^{\circ}\text{C}$ max) and a linear analog output voltage that is inversely proportional to temperature. The 1.5-V supply voltage operation, $5.4\text{-}\mu\text{A}$ quiescent current, and 0.7-ms power-on time enable effective power-cycling architectures to minimize power consumption for battery-powered applications such as drones and sensor nodes. The LMT84LPG through-hole TO-92S package fast thermal time constant supports off-board time-temperature sensitive applications such as smoke and heat detectors. The LMT84-Q1 device is AEC-Q100 Grade 0 qualified and maintains $\pm 2.7^{\circ}\text{C}$ maximum accuracy over the full operating temperature range without calibration; this makes the LMT84-Q1 suitable for automotive applications such as infotainment, cluster, and powertrain systems. The accuracy over the wide operating range and other features make the LMT84 and LMT84-Q1 excellent alternative to thermistors.

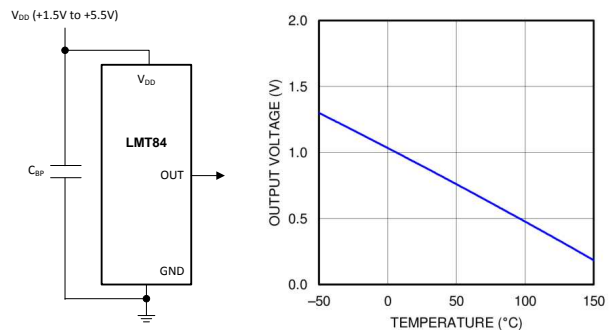
For devices with different average sensor gains and comparable accuracy, refer to [Comparable Alternative Devices](#) for alternative devices in the LMT8x family.

Device Information⁽¹⁾

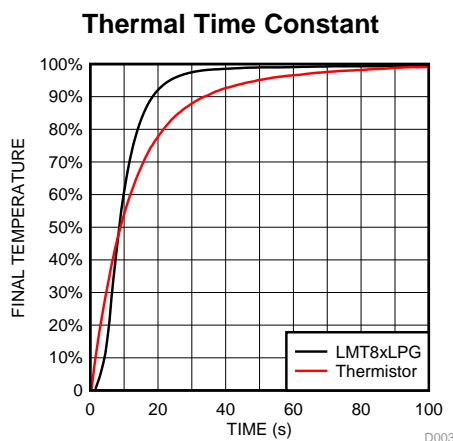
| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|-------------|------------|-------------------|
| LMT84 | SOT (5) | 2.00 mm x 1.25 mm |
| | TO-92 (3) | 4.3 mm x 3.5 mm |
| | TO-92S (3) | 4.0 mm x 3.15 mm |
| LMT84-Q1 | SOT (5) | 2.00 mm x 1.25 mm |

- (1) For all available packages, see the orderable addendum addendum at the end of the data sheet.

Output Voltage vs Temperature



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* Fast thermal response NTC



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Changes from Revision C (October 2015) to Revision D | Page |
|--|-------------|
| • Updated data sheet text to the latest documentation and translations standards | 1 |
| • Added AEC-Q100 automotive qualification bullets to <i>Features</i> | 1 |
| • Added Time Constant graph | 1 |
| • Removed disk drivers, games, wireless transceivers, and cell phones from <i>Applications</i> | 1 |
| • Added LPG (TO-92S) package | 3 |
| • Added Figure 10 to <i>Typical Characteristics</i> | 7 |

| Changes from Revision B (May 2014) to Revision C | Page |
|---|-------------|
| • Deleted all mentions of TO-126 package | 1 |
| • Added TO-92 LPM pin configuration graphic | 3 |
| • Changed Handling Ratings to ESD Ratings and moved Storage Temperature to Absolute Maximum Ratings table | 4 |
| • Changed KV to V | 4 |
| • Added layout recommendation for TO-92 LP and LPM packages | 15 |

| Changes from Revision A (June 2013) to Revision B | Page |
|---|-------------|
| • Changed data sheet flow and layout to conform with new TI standards. Added the following sections: Application and Implementation, Power Supply Recommendations, Layout, Device and Documentation Support, Mechanical, Packaging, and Orderable Information. | 1 |
| • Added TO-92 and TO-126 package information throughout document. | 1 |
| • Changed from 450°C/W to 275 °C/W. New specification is derived using TI 's latest methodology. | 5 |
| • Deleted Note: The input current is leakage only and is highest at high temperature. It is typically only 0.001 μA. The 1 μA limit is solely based on a testing limitation and does not reflect the actual performance of the part. | 6 |

5 Device Comparison Tables

Table 1. Available Device Packages

| ORDER NUMBER ⁽¹⁾ | PACKAGE | PIN | BODY SIZE (NOM) | MOUNTING TYPE |
|-----------------------------|--------------------------------------|-----|-------------------|------------------------------|
| LMT84DCK | SOT (AKA ⁽²⁾ : SC70, DCK) | 5 | 2.00 mm × 1.25 mm | Surface Mount |
| LMT84LP | TO-92 (AKA ⁽²⁾ : LP) | 3 | 4.30 mm × 3.50 mm | Through-hole; straight leads |
| LMT84LPG | TO-92S (AKA ⁽²⁾ : LPG) | 3 | 4.00 mm × 3.15 mm | Through-hole; straight leads |
| LMT84LPM | TO-92 (AKA ⁽²⁾ : LPM) | 3 | 4.30 mm × 3.50 mm | Through-hole; formed leads |
| LMT84DCK-Q1 | SOT (AKA ⁽²⁾ : SC70, DCK) | 5 | 2.00 mm × 1.25 mm | Surface Mount |

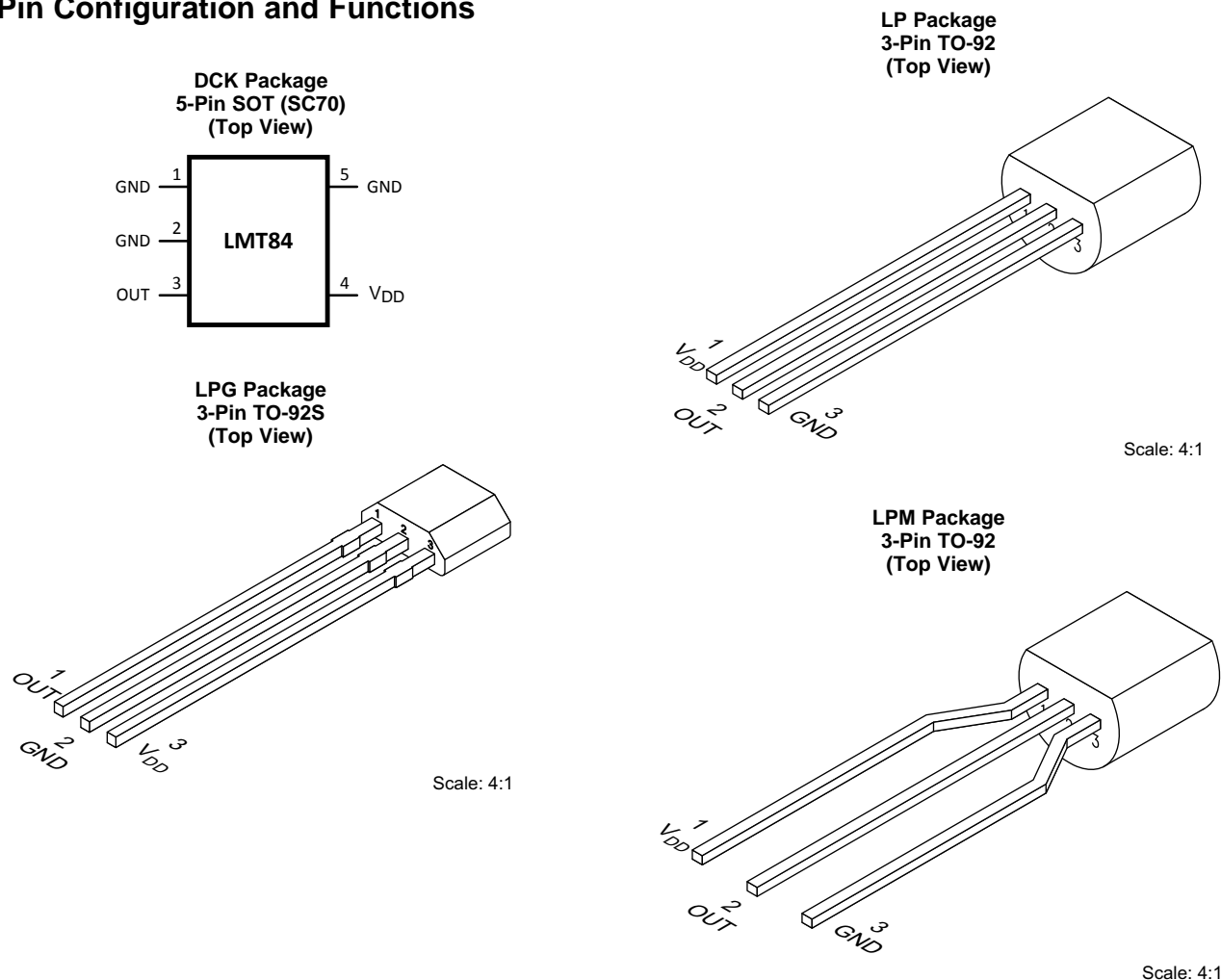
(1) For all available packages and complete order numbers, see the Package Option addendum at the end of the data sheet.

(2) AKA = Also Known As

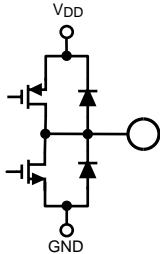
Table 2. Comparable Alternative Devices

| DEVICE NAME | AVERAGE OUTPUT SENSOR GAIN | POWER SUPPLY RANGE |
|--------------------------------|----------------------------|--------------------|
| LMT84/LMT84-Q1 | -5.5 mV/°C | 1.5 V to 5.5 V |
| LMT85/LMT85-Q1 | -8.2 mV/°C | 1.8 V to 5.5 V |
| LMT86/LMT86-Q1 | -10.9 mV/°C | 2.2 V to 5.5 V |
| LMT87/LMT87-Q1 | -13.6 mV/°C | 2.7 V to 5.5 V |

6 Pin Configuration and Functions



Pin Functions

| PIN | | | | DESCRIPTION | | |
|-----------------|-------------------------|-------|--------|---------------|--|---|
| NAME | SOT (SC70) | TO-92 | TO-92S | TYPE | EQUIVALENT CIRCUIT | FUNCTION |
| GND | 1, 2 ⁽¹⁾ , 5 | 1 | 2 | Ground | N/A | Power Supply Ground |
| OUT | 3 | 2 | 1 | Analog Output |  | Outputs a voltage that is inversely proportional to temperature |
| V _{DD} | 4 | 3 | 3 | Power | N/A | Positive Supply Voltage |

(1) Direct connection to the back side of the die

7 Specifications

7.1 Absolute Maximum Ratings

See ⁽¹⁾⁽²⁾

| | MIN | MAX | UNIT |
|---|------|-------------------------|------|
| Supply voltage | -0.3 | 6 | V |
| Voltage at output pin | -0.3 | (V _{DD} + 0.5) | V |
| Output current | -7 | 7 | mA |
| Input current at any pin ⁽³⁾ | -5 | 5 | mA |
| Maximum junction temperature (T _{JMAX}) | | 150 | °C |
| Storage temperature T _{stg} | -65 | 150 | °C |

- Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- Soldering process must comply with Reflow Temperature Profile specifications. Refer to www.ti.com/packaging.*
- When the input voltage (V_I) at any pin exceeds power supplies (V_I < GND or V_I > V), the current at that pin should be limited to 5 mA.

7.2 ESD Ratings – LMT84

| | | | VALUE | UNIT |
|---------------------------------|-------------------------|--|-------|------|
| LMT84LP in TO-92/TO-92S package | | | | |
| V _(ESD) | Electrostatic discharge | Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾⁽²⁾ | ±2500 | V |
| | | Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽³⁾ | ±1000 | |
| LMT84DCK in SC70 package | | | | |
| V _(ESD) | Electrostatic discharge | Human-body model (HBM), per JESD22-A114 ⁽²⁾ | ±2500 | V |
| | | Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽³⁾ | ±1000 | |

- JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- The human body model is a 100-pF capacitor discharged through a 1.5-kΩ resistor into each pin.
- JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 ESD Ratings – LMT84-Q1

| | | | VALUE | UNIT |
|-----------------------------|-------------------------|---|-------|------|
| LMT84DCK-Q1 in SC70 package | | | | |
| V _(ESD) | Electrostatic discharge | Human-body model (HBM), per AEC Q100-002 ⁽¹⁾ | ±2500 | V |
| | | Charged-device model (CDM), per AEC Q100-011 | ±1000 | |

- AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

7.4 Recommended Operating Conditions

| | MIN | MAX | UNIT |
|------------------------------------|---|-----|------|
| Specified temperature | $T_{\text{MIN}} \leq T_A \leq T_{\text{MAX}}$ | | °C |
| | $-50 \leq T_A \leq 150$ | | °C |
| Supply voltage (V_{DD}) | 1.5 | 5.5 | V |

7.5 Thermal Information⁽¹⁾

| THERMAL METRIC ⁽²⁾ | LMT84/ LMT84-Q1 | LMT84LP | LMT84LPG | UNIT |
|--|--------------------|----------------|--------------|------|
| | DCK (SOT/SC70) | LP/LPM (TO-92) | LPG (TO-92S) | |
| | 5 PINS | 3 PINS | 3 PINS | |
| $R_{\theta\text{JA}}$ Junction-to-ambient thermal resistance ⁽³⁾⁽⁴⁾ | 275 | 167 | 130.4 | °C/W |
| $R_{\theta\text{JC(top)}}$ Junction-to-case (top) thermal resistance | 84 | 90 | 64.2 | °C/W |
| $R_{\theta\text{JB}}$ Junction-to-board thermal resistance | 56 | 146 | 106.2 | °C/W |
| Ψ_{JT} Junction-to-top characterization parameter | 1.2 | 35 | 14.6 | °C/W |
| Ψ_{JB} Junction-to-board characterization parameter | 55 | 146 | 106.2 | °C/W |

- (1) For information on self-heating and thermal response time see section [Mounting and Thermal Conductivity](#).
- (2) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report.
- (3) The junction to ambient thermal resistance ($R_{\theta\text{JA}}$) under natural convection is obtained in a simulation on a JEDEC-standard, High-K board as specified in JESD51-7, in an environment described in JESD51-2. Exposed pad packages assume that thermal vias are included in the PCB, per JESD 51-5.
- (4) Changes in output due to self heating can be computed by multiplying the internal dissipation by the thermal resistance.

7.6 Accuracy Characteristics

These limits do not include DC load regulation. These stated accuracy limits are with reference to the values in [Table 3](#).

| PARAMETER | TEST CONDITIONS | MIN ⁽¹⁾ | TYP ⁽²⁾ | MAX ⁽¹⁾ | UNIT |
|-------------------------------------|---|--------------------|--------------------|--------------------|------|
| Temperature accuracy ⁽³⁾ | 70°C to 150°C; V _{DD} = 1.5 V to 5.5 V | -2.7 | ±0.6 | 2.7 | °C |
| | 0°C to 70°C; V _{DD} = 1.5 V to 5.5 V | -2.7 | ±0.9 | 2.7 | °C |
| | -50°C to +0°C; V _{DD} = 1.6 V to 5.5 V | -2.7 | ±0.9 | 2.7 | °C |
| | -50°C to +150°C; V _{DD} = 2.3 V to 5.5 V | | ±0.4 | | °C |

- (1) Limits are specified to TI's AOQL (Average Outgoing Quality Level).
- (2) Typicals are at T_J = T_A = 25°C and represent most likely parametric norm.
- (3) Accuracy is defined as the error between the measured and reference output voltages, tabulated in [Table 3](#) at the specified conditions of supply gain setting, voltage, and temperature (expressed in °C). Accuracy limits include line regulation within the specified conditions. Accuracy limits do not include load regulation; they assume no DC load.

7.7 Electrical Characteristics

Unless otherwise noted, these specifications apply for V_{DD} = +1.5 V to +5.5 V. minimum and maximum limits apply for T_A = T_J = T_{MIN} to T_{MAX}; typical values apply for T_A = T_J = 25°C.

| PARAMETER | TEST CONDITIONS | MIN ⁽¹⁾ | TYP ⁽²⁾ | MAX ⁽¹⁾ | UNIT |
|--|---|--------------------|--------------------|--------------------|-------|
| Sensor gain | | | -5.5 | | mV/°C |
| Load regulation ⁽³⁾ | Source ≤ 50 μA, (V _{DD} - V _{OUT}) ≥ 200 mV | -1 | -0.22 | | mV |
| | Sink ≤ 50 μA, V _{OUT} ≥ 200 mV | | 0.26 | 1 | mV |
| Line regulation ⁽⁴⁾ | | | 200 | | μV/V |
| I _S Supply current | T _A = 30°C to 150°C, (V _{DD} - V _{OUT}) ≥ 100 mV | | 5.4 | 8.1 | μA |
| | T _A = -50°C to 150°C, (V _{DD} - V _{OUT}) ≥ 100 mV | | 5.4 | 9 | μA |
| C _L Output load capacitance | | | 1100 | | pF |
| Power-on time ⁽⁵⁾ | C _L = 0 pF to 1100 pF | | 0.7 | 1.9 | ms |
| Output drive | | | ±50 | | μA |

- (1) Limits are specific to TI's AOQL (Average Outgoing Quality Level).
- (2) Typicals are at T_J = T_A = 25°C and represent most likely parametric norm.
- (3) Source currents are flowing out of the LMT84-xx. Sink currents are flowing into the LMT84-xx.
- (4) Line regulation (DC) is calculated by subtracting the output voltage at the highest supply voltage from the output voltage at the lowest supply voltage. The typical DC line regulation specification does not include the output voltage shift discussed in [Output Voltage Shift](#).
- (5) Specified by design and characterization.

7.8 Typical Characteristics

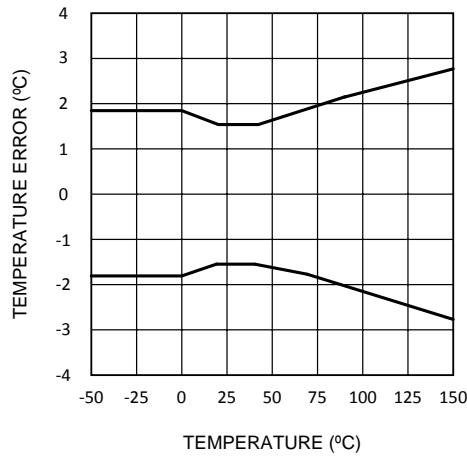


Figure 1. Temperature Error vs Temperature

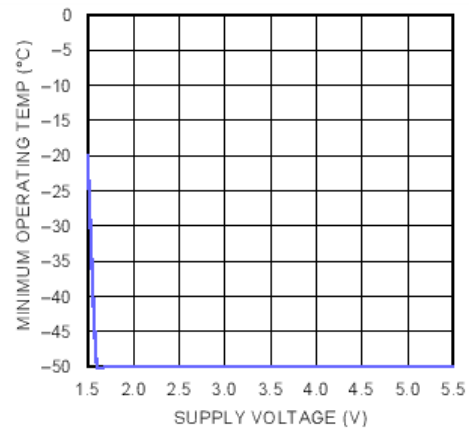


Figure 2. Minimum Operating Temperature vs Supply Voltage

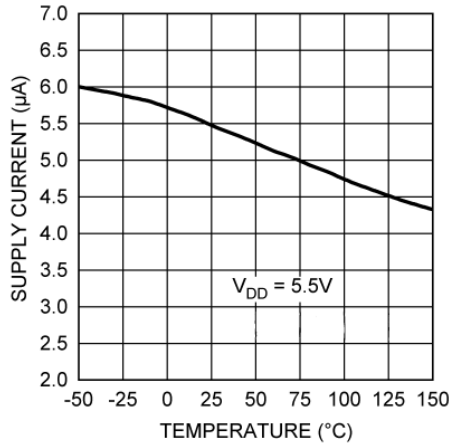


Figure 3. Supply Current vs Temperature

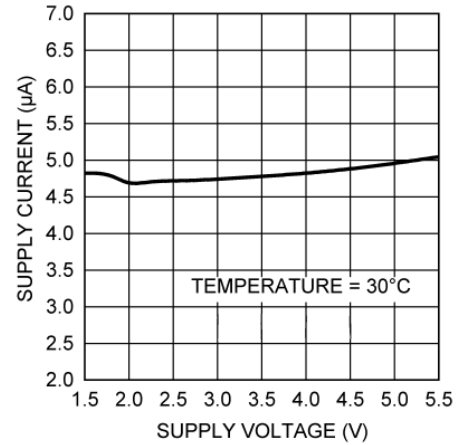


Figure 4. Supply Current vs Supply Voltage

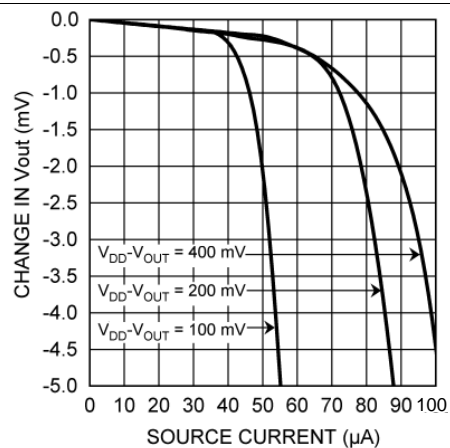


Figure 5. Load Regulation, Sourcing Current

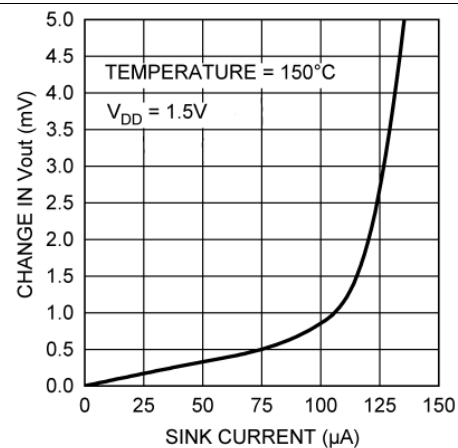


Figure 6. Load Regulation, Sinking Current

Typical Characteristics (continued)

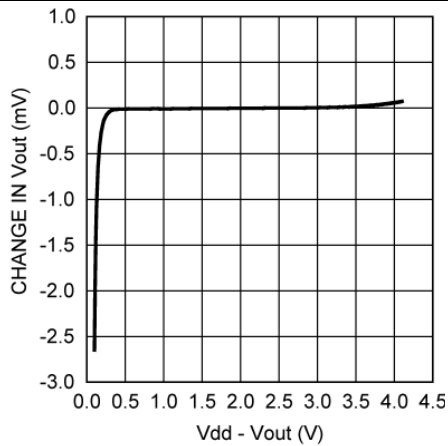


Figure 7. Change in Vout vs Overhead Voltage

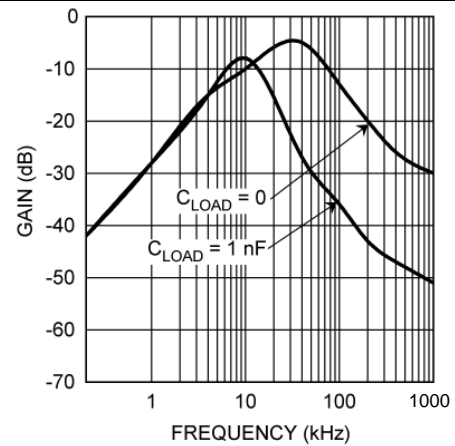


Figure 8. Supply-Noise Gain vs Frequency

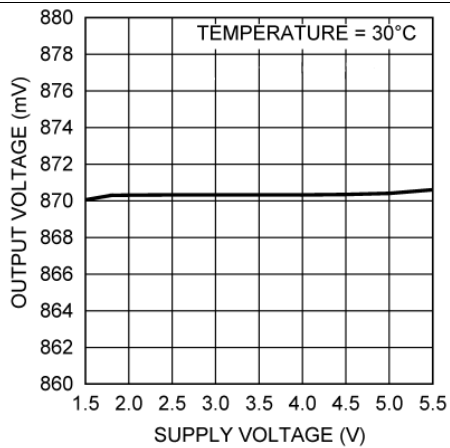


Figure 9. Output Voltage vs Supply Voltage

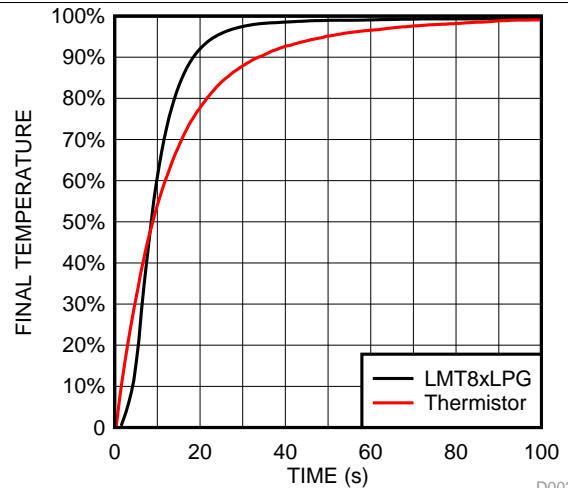


Figure 10. LMT84LPG Thermal Response vs Common Leaded Thermistor With 1.2-m/s Airflow

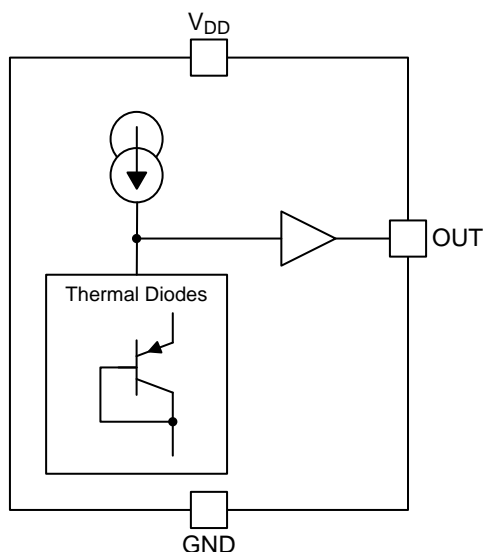
8 Detailed Description

8.1 Overview

The LMT84 and LMT84-Q1 are analog output temperature sensors. The electrical characteristics of the LMT84 and LMT84-Q1 are identical, so for clarity, the devices will be subsequently referred to as simply LMT84. The temperature-sensing element is comprised of a simple base emitter junction that is forward biased by a current source. The temperature-sensing element is then buffered by an amplifier and provided to the OUT pin. The amplifier has a simple push-pull output stage thus providing a low impedance output source.

8.2 Functional Block Diagram

Full-Range Celsius Temperature Sensor (–50°C to +150°C)



8.3 Feature Description

8.3.1 LMT84 Transfer Function

The output voltage of the LMT84, across the complete operating temperature range, is shown in [Table 3](#). This table is the reference from which the LMT84 accuracy specifications (listed in the [Accuracy Characteristics](#) section) are determined. This table can be used, for example, in a host processor look-up table. A file containing this data is available for download at the [LMT84](#) product folder under *Tools and Software Models*.

Table 3. LMT84 Transfer Table

| TEMP (°C) | V _{OUT} (mV) | TEMP (°C) | V _{OUT} (mV) | TEMP (°C) | V _{OUT} (mV) | TEMP (°C) | V _{OUT} (mV) | TEMP (°C) | V _{OUT} (mV) |
|-----------|-----------------------|-----------|-----------------------|-----------|-----------------------|-----------|-----------------------|-----------|-----------------------|
| –50 | 1299 | –10 | 1088 | 30 | 871 | 70 | 647 | 110 | 419 |
| –49 | 1294 | –9 | 1082 | 31 | 865 | 71 | 642 | 111 | 413 |
| –48 | 1289 | –8 | 1077 | 32 | 860 | 72 | 636 | 112 | 407 |
| –47 | 1284 | –7 | 1072 | 33 | 854 | 73 | 630 | 113 | 401 |
| –46 | 1278 | –6 | 1066 | 34 | 849 | 74 | 625 | 114 | 396 |
| –45 | 1273 | –5 | 1061 | 35 | 843 | 75 | 619 | 115 | 390 |
| –44 | 1268 | –4 | 1055 | 36 | 838 | 76 | 613 | 116 | 384 |
| –43 | 1263 | –3 | 1050 | 37 | 832 | 77 | 608 | 117 | 378 |
| –42 | 1257 | –2 | 1044 | 38 | 827 | 78 | 602 | 118 | 372 |
| –41 | 1252 | –1 | 1039 | 39 | 821 | 79 | 596 | 119 | 367 |
| –40 | 1247 | 0 | 1034 | 40 | 816 | 80 | 591 | 120 | 361 |
| –39 | 1242 | 1 | 1028 | 41 | 810 | 81 | 585 | 121 | 355 |

Feature Description (continued)
Table 3. LMT84 Transfer Table (continued)

| TEMP (°C) | V _{OUT} (mV) | TEMP (°C) | V _{OUT} (mV) | TEMP (°C) | V _{OUT} (mV) | TEMP (°C) | V _{OUT} (mV) | TEMP (°C) | V _{OUT} (mV) |
|-----------|-----------------------|-----------|-----------------------|-----------|-----------------------|-----------|-----------------------|-----------|-----------------------|
| -38 | 1236 | 2 | 1023 | 42 | 804 | 82 | 579 | 122 | 349 |
| -37 | 1231 | 3 | 1017 | 43 | 799 | 83 | 574 | 123 | 343 |
| -36 | 1226 | 4 | 1012 | 44 | 793 | 84 | 568 | 124 | 337 |
| -35 | 1221 | 5 | 1007 | 45 | 788 | 85 | 562 | 125 | 332 |
| -34 | 1215 | 6 | 1001 | 46 | 782 | 86 | 557 | 126 | 326 |
| -33 | 1210 | 7 | 996 | 47 | 777 | 87 | 551 | 127 | 320 |
| -32 | 1205 | 8 | 990 | 48 | 771 | 88 | 545 | 128 | 314 |
| -31 | 1200 | 9 | 985 | 49 | 766 | 89 | 539 | 129 | 308 |
| -30 | 1194 | 10 | 980 | 50 | 760 | 90 | 534 | 130 | 302 |
| -29 | 1189 | 11 | 974 | 51 | 754 | 91 | 528 | 131 | 296 |
| -28 | 1184 | 12 | 969 | 52 | 749 | 92 | 522 | 132 | 291 |
| -27 | 1178 | 13 | 963 | 53 | 743 | 93 | 517 | 133 | 285 |
| -26 | 1173 | 14 | 958 | 54 | 738 | 94 | 511 | 134 | 279 |
| -25 | 1168 | 15 | 952 | 55 | 732 | 95 | 505 | 135 | 273 |
| -24 | 1162 | 16 | 947 | 56 | 726 | 96 | 499 | 136 | 267 |
| -23 | 1157 | 17 | 941 | 57 | 721 | 97 | 494 | 137 | 261 |
| -22 | 1152 | 18 | 936 | 58 | 715 | 98 | 488 | 138 | 255 |
| -21 | 1146 | 19 | 931 | 59 | 710 | 99 | 482 | 139 | 249 |
| -20 | 1141 | 20 | 925 | 60 | 704 | 100 | 476 | 140 | 243 |
| -19 | 1136 | 21 | 920 | 61 | 698 | 101 | 471 | 141 | 237 |
| -18 | 1130 | 22 | 914 | 62 | 693 | 102 | 465 | 142 | 231 |
| -17 | 1125 | 23 | 909 | 63 | 687 | 103 | 459 | 143 | 225 |
| -16 | 1120 | 24 | 903 | 64 | 681 | 104 | 453 | 144 | 219 |
| -15 | 1114 | 25 | 898 | 65 | 676 | 105 | 448 | 145 | 213 |
| -14 | 1109 | 26 | 892 | 66 | 670 | 106 | 442 | 146 | 207 |
| -13 | 1104 | 27 | 887 | 67 | 664 | 107 | 436 | 147 | 201 |
| -12 | 1098 | 28 | 882 | 68 | 659 | 108 | 430 | 148 | 195 |
| -11 | 1093 | 29 | 876 | 69 | 653 | 109 | 425 | 149 | 189 |
| | | | | | | | | 150 | 183 |

Although the LMT84 is very linear, the response does have a slight umbrella parabolic shape. This shape is very accurately reflected in [Table 3](#). The transfer table can be calculated by using the parabolic equation ([Equation 1](#)).

$$V_{\text{TEMP}} (\text{mV}) = 870.6 \text{mV} - \left[5.506 \frac{\text{mV}}{^{\circ}\text{C}} (T - 30^{\circ}\text{C}) \right] - \left[0.00176 \frac{\text{mV}}{^{\circ}\text{C}^2} (T - 30^{\circ}\text{C})^2 \right] \quad (1)$$

The parabolic equation is an approximation of the transfer table and the accuracy of the equation degrades slightly at the temperature range extremes. [Equation 1](#) can be solved for T, resulting in:

$$T = \frac{5.506 - \sqrt{(-5.506)^2 + 4 \times 0.00176 \times (870.6 - V_{\text{TEMP}} (\text{mV}))}}{2 \times (-0.00176)} + 30 \quad (2)$$

For an even less accurate linear approximation, a line can easily be calculated over the desired temperature range from the table using the two-point equation ([Equation 3](#)):

$$V - V_1 = \left(\frac{V_2 - V_1}{T_2 - T_1} \right) \times (T - T_1)$$

where

- V is in mV,
- T is in °C,
- T₁ and V₁ are the coordinates of the lowest temperature,
- and T₂ and V₂ are the coordinates of the highest temperature.

(3)

For example, if the user wanted to resolve this equation, over a temperature range of 20°C to 50°C, they would proceed as follows:

$$V - 925 \text{ mV} = \left(\frac{760 \text{ mV} - 925 \text{ mV}}{50^\circ\text{C} - 20^\circ\text{C}} \right) \times (T - 20^\circ\text{C}) \quad (4)$$

$$V - 925 \text{ mV} = (-5.50 \text{ mV} / ^\circ\text{C}) \times (T - 20^\circ\text{C}) \quad (5)$$

$$V = (-5.50 \text{ mV} / ^\circ\text{C}) \times T + 1035 \text{ mV} \quad (6)$$

Using this method of linear approximation, the transfer function can be approximated for one or more temperature ranges of interest.

8.4 Device Functional Modes

8.4.1 Mounting and Thermal Conductivity

The LMT84 can be applied easily in the same way as other integrated-circuit temperature sensors. It can be glued or cemented to a surface.

To ensure good thermal conductivity, the backside of the LMT84 die is directly attached to the GND pin. The temperatures of the lands and traces to the other leads of the LMT84 will also affect the temperature reading.

Alternatively, the LMT84 can be mounted inside a sealed-end metal tube, and can then be dipped into a bath or screwed into a threaded hole in a tank. As with any IC, the LMT84 and accompanying wiring and circuits must be kept insulated and dry, to avoid leakage and corrosion. This is especially true if the circuit may operate at cold temperatures where condensation can occur. If moisture creates a short circuit from the output to ground or V_{DD} , the output from the LMT84 will not be correct. Printed-circuit coatings are often used to ensure that moisture cannot corrode the leads or circuit traces.

The thermal resistance junction to ambient ($R_{\theta JA}$ or θ_{JA}) is the parameter used to calculate the rise of a device junction temperature due to its power dissipation. Use [Equation 7](#) to calculate the rise in the LMT84 die temperature:

$$T_J = T_A + \theta_{JA} [(V_{DD} I_S) + (V_{DD} - V_O) I_L]$$

where

- T_A is the ambient temperature,
- I_S is the supply current,
- I_L is the load current on the output,
- and V_O is the output voltage. (7)

For example, in an application where $T_A = 30^\circ\text{C}$, $V_{DD} = 5 \text{ V}$, $I_S = 5.4 \mu\text{A}$, $V_{OUT} = 871 \text{ mV}$, and $I_L = 2 \mu\text{A}$, the junction temperature would be 30.015°C , showing a self-heating error of only 0.015°C . Because the junction temperature of the LMT84 device is the actual temperature being measured, take care to minimize the load current that the LMT84 is required to drive. [Thermal Information](#) shows the thermal resistance of the LMT84.

8.4.2 Output Noise Considerations

A push-pull output gives the LMT84 the ability to sink and source significant current. This is beneficial when, for example, driving dynamic loads like an input stage on an analog-to-digital converter (ADC). In these applications the source current is required to quickly charge the input capacitor of the ADC. The LMT84 is ideal for this and other applications which require strong source or sink current.

The LMT84 supply-noise gain (the ratio of the AC signal on V_{OUT} to the AC signal on V_{DD}) was measured during bench tests. The typical attenuation is shown in [Figure 8](#) found in the [Typical Characteristics](#) section. A load capacitor on the output can help to filter noise.

For operation in very noisy environments, some bypass capacitance should be present on the supply within approximately 5 centimeters of the LMT84.

Device Functional Modes (continued)

8.4.3 Capacitive Loads

The LMT84 handles capacitive loading well. In an extremely noisy environment, or when driving a switched sampling input on an ADC, it may be necessary to add some filtering to minimize noise coupling. Without any precautions, the LMT84 can drive a capacitive load less than or equal to 1100 pF as shown in [Figure 11](#). For capacitive loads greater than 1100 pF, a series resistor may be required on the output, as shown in [Figure 12](#).

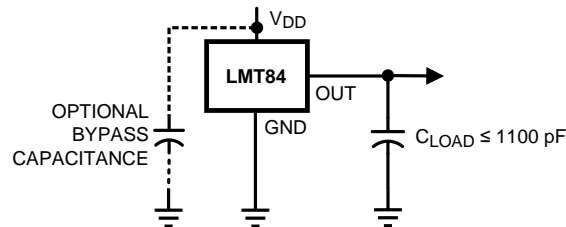


Figure 11. LMT84 No Decoupling Required for Capacitive Loads Less Than 1100 pF

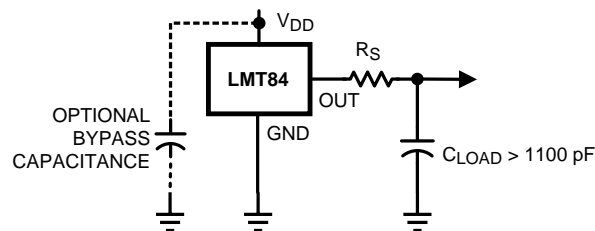


Figure 12. LMT84 With Series Resistor for Capacitive Loading Greater Than 1100 pF

Table 4. Recommended Series Resistor Values

| C_{LOAD} | MINIMUM R_S |
|------------------|----------------|
| 1.1 nF to 99 nF | 3 k Ω |
| 100 nF to 999 nF | 1.5 k Ω |
| 1 μ F | 800 Ω |

8.4.4 Output Voltage Shift

The LMT84 is very linear over temperature and supply voltage range. Due to the intrinsic behavior of an NMOS or PMOS rail-to-rail buffer, a slight shift in the output can occur when the supply voltage is ramped over the operating range of the device. The location of the shift is determined by the relative levels of V_{DD} and V_{OUT} . The shift typically occurs when $V_{DD} - V_{OUT} = 1$ V.

This slight shift (a few millivolts) takes place over a wide change (approximately 200 mV) in V_{DD} or V_{OUT} . Because the shift takes place over a wide temperature change of 5°C to 20°C, V_{OUT} is always monotonic. The accuracy specifications in the [Accuracy Characteristics](#) table already include this possible shift.

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Applications Information

The LMT84 features make it suitable for many general temperature-sensing applications. It can operate down to 1.5-V supply with 5.4- μ A power consumption, making it ideal for battery-powered devices. Package options like the through-hole TO-92 package allow the LMT84 to be mounted onboard, off-board, to a heat sink, or on multiple unique locations in the same application.

9.2 Typical Applications

9.2.1 Connection to an ADC

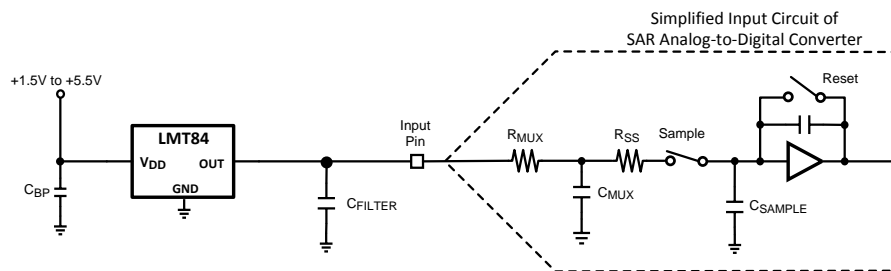


Figure 13. Suggested Connection to a Sampling Analog-to-Digital Converter Input Stage

9.2.1.1 Design Requirements

Most CMOS ADCs found in microcontrollers and ASICs have a sampled data comparator input structure. When the ADC charges the sampling cap, it requires instantaneous charge from the output of the analog source such as the LMT84 temperature sensor and many op amps. This requirement is easily accommodated by the addition of a capacitor (C_{FILTER}).

9.2.1.2 Detailed Design Procedure

The size of C_{FILTER} depends on the size of the sampling capacitor and the sampling frequency. Because not all ADCs have identical input stages, the charge requirements will vary. This general ADC application is shown as an example only.

9.2.1.3 Application Curve

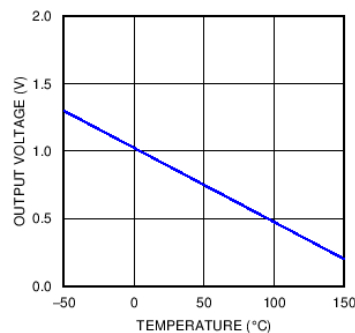


Figure 14. Analog Output Transfer Function

Typical Applications (continued)

9.2.2 Conserving Power Dissipation With Shutdown

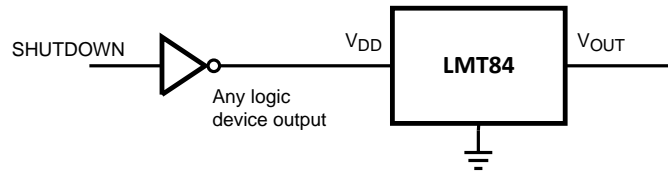


Figure 15. Simple Shutdown Connection of the LMT84

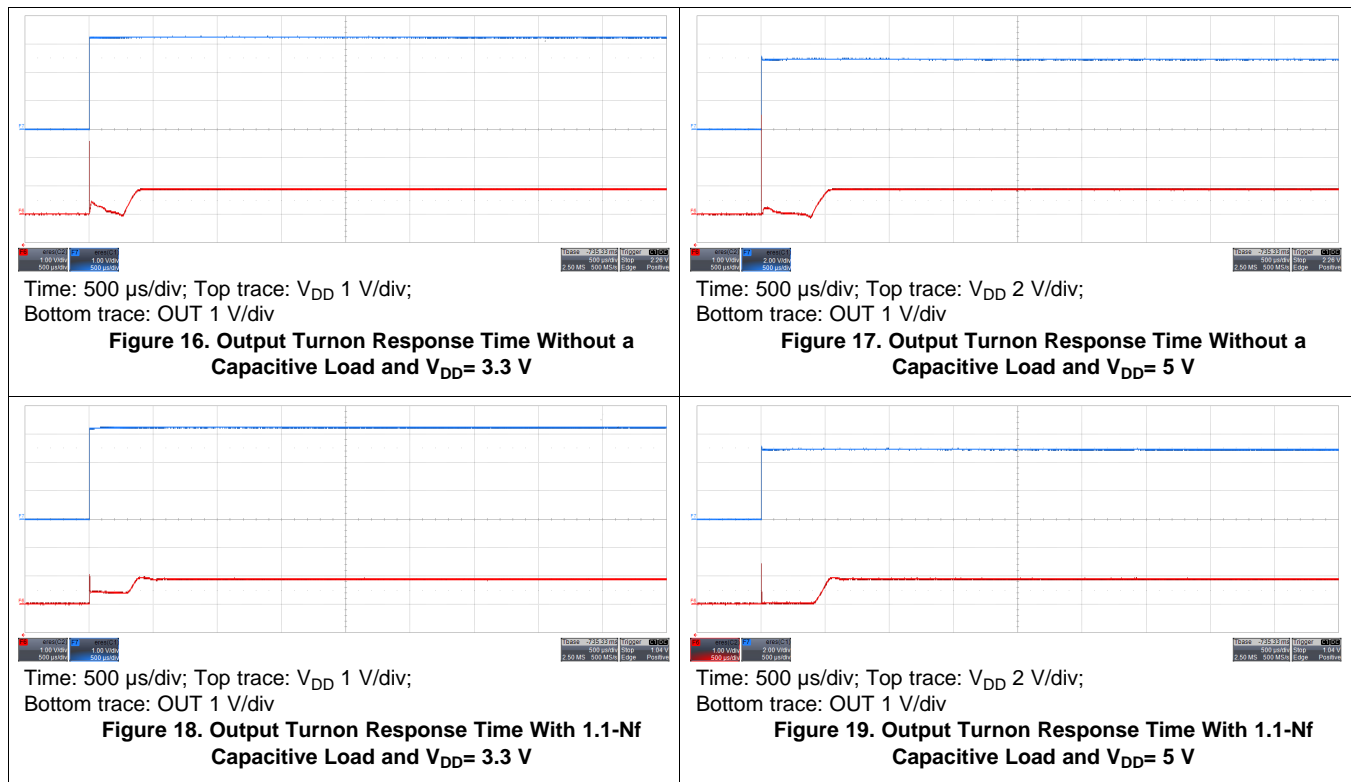
9.2.2.1 Design Requirements

Because the power consumption of the LMT84 is less than 9 μ A, it can simply be powered directly from any logic gate output and therefore not require a specific shutdown pin. The device can even be powered directly from a microcontroller GPIO. In this way, it can easily be turned off for cases such as battery-powered systems where power savings are critical.

9.2.2.2 Detailed Design Procedure

Simply connect the V_{DD} pin of the LMT84 directly to the logic shutdown signal from a microcontroller.

9.2.2.3 Application Curves



10 Power Supply Recommendations



The low supply current and supply range (1.5 V to 5.5 V) of the LMT84 allow the device to easily be powered from many sources. Power supply bypassing is optional and is mainly dependent on the noise on the power supply used. In noisy systems, it may be necessary to add bypass capacitors to lower the noise that is coupled to the output of the LMT84.

11 Layout

11.1 Layout Guidelines

The LMT84 is extremely simple to layout. If a power-supply bypass capacitor is used, it should be connected as shown in the [Layout Examples](#).

11.2 Layout Examples

-  VIA to ground plane
-  VIA to power plane

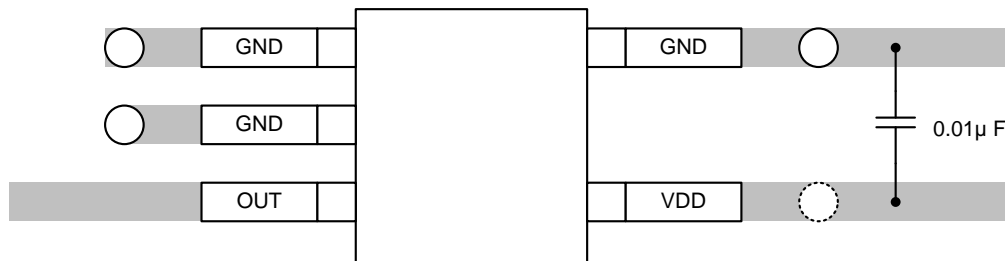


Figure 20. SC70 Package Recommended Layout

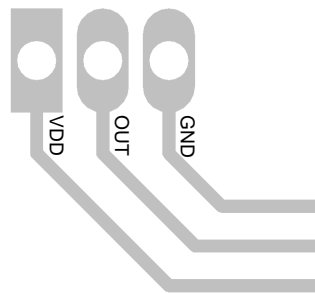


Figure 21. TO-92 LP Package Recommended Layout

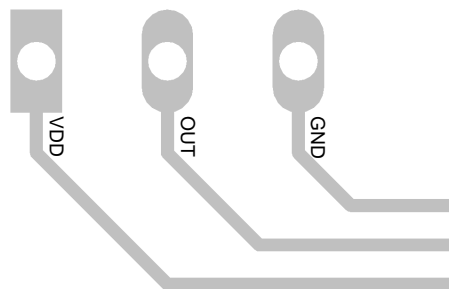


Figure 22. TO-92 LPM Package Recommended Layout

12 Device and Documentation Support

12.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 5. Related Links

| PARTS | PRODUCT FOLDER | SAMPLE & BUY | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|----------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|
| LMT84 | Click here | Click here | Click here | Click here | Click here |
| LMT84-Q1 | Click here | Click here | Click here | Click here | Click here |

12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.4 Trademarks

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

12.5 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| LMT84DCKR | ACTIVE | SC70 | DCK | 5 | 3000 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -50 to 150 | BNA | Samples |
| LMT84DCKT | ACTIVE | SC70 | DCK | 5 | 250 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -50 to 150 | BNA | Samples |
| LMT84LP | ACTIVE | TO-92 | LP | 3 | 1800 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | -50 to 150 | LMT84 | Samples |
| LMT84LPG | ACTIVE | TO-92 | LPG | 3 | 1000 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | -50 to 150 | LMT84 | Samples |
| LMT84LPGM | ACTIVE | TO-92 | LPG | 3 | 3000 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | -50 to 150 | LMT84 | Samples |
| LMT84LPM | ACTIVE | TO-92 | LP | 3 | 2000 | Green (RoHS & no Sb/Br) | CU SN | N / A for Pkg Type | -50 to 150 | LMT84 | Samples |
| LMT84QDCKRQ1 | ACTIVE | SC70 | DCK | 5 | 3000 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -50 to 150 | BOA | Samples |
| LMT84QDCKTQ1 | ACTIVE | SC70 | DCK | 5 | 250 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -50 to 150 | BOA | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=100ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF LMT84, LMT84-Q1 :

- Catalog: [LMT84](#)
- Automotive: [LMT84-Q1](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| LMT84DCKR | SC70 | DCK | 5 | 3000 | 178.0 | 8.4 | 2.25 | 2.45 | 1.2 | 4.0 | 8.0 | Q3 |
| LMT84DCKT | SC70 | DCK | 5 | 250 | 178.0 | 8.4 | 2.25 | 2.45 | 1.2 | 4.0 | 8.0 | Q3 |
| LMT84QDCKRQ1 | SC70 | DCK | 5 | 3000 | 178.0 | 8.4 | 2.25 | 2.45 | 1.2 | 4.0 | 8.0 | Q3 |
| LMT84QDCKTQ1 | SC70 | DCK | 5 | 250 | 178.0 | 8.4 | 2.25 | 2.45 | 1.2 | 4.0 | 8.0 | Q3 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| LMT84DCKR | SC70 | DCK | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| LMT84DCKT | SC70 | DCK | 5 | 250 | 210.0 | 185.0 | 35.0 |
| LMT84QDCKRQ1 | SC70 | DCK | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| LMT84QDCKTQ1 | SC70 | DCK | 5 | 250 | 210.0 | 185.0 | 35.0 |

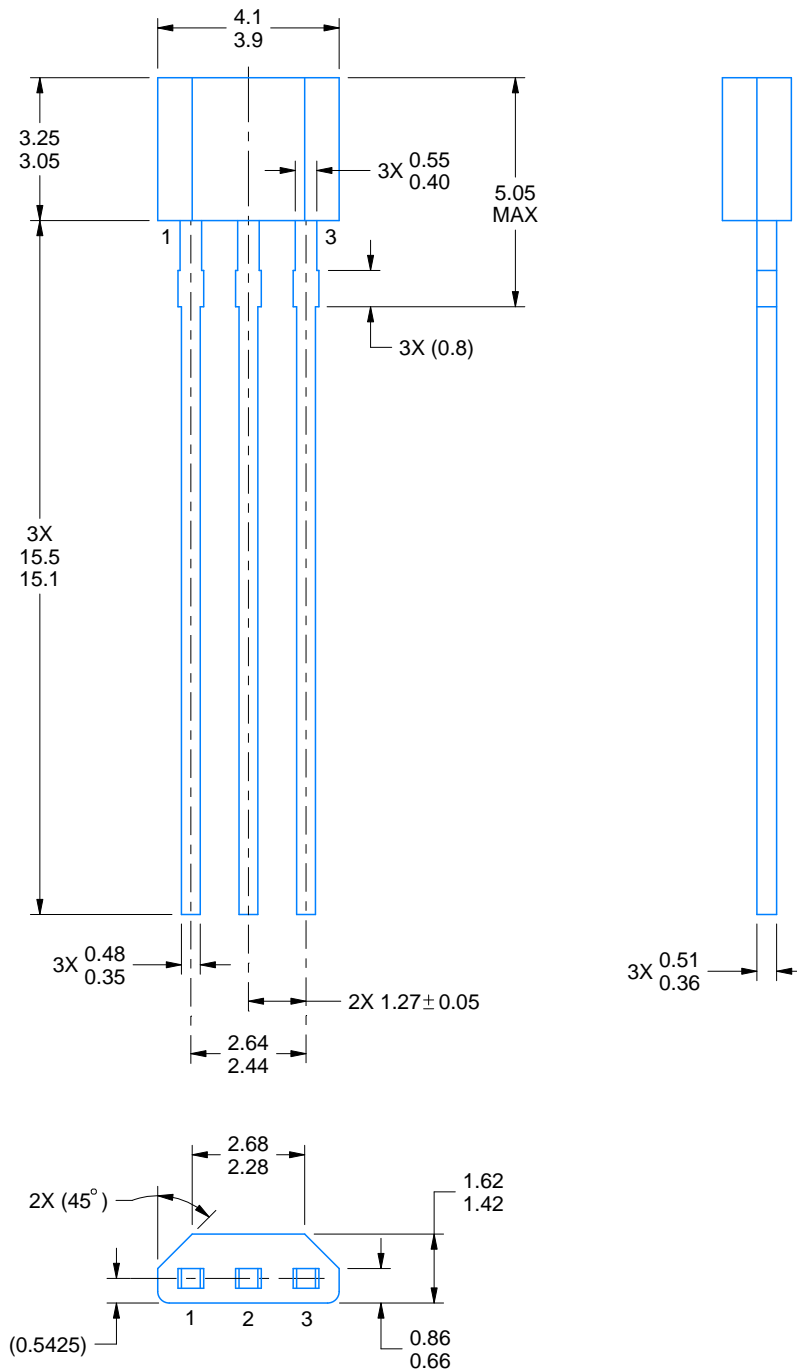
LPG0003A



PACKAGE OUTLINE

TO-92 - 5.05 mm max height

TRANSISTOR OUTLINE



4221343/C 01/2018

NOTES:

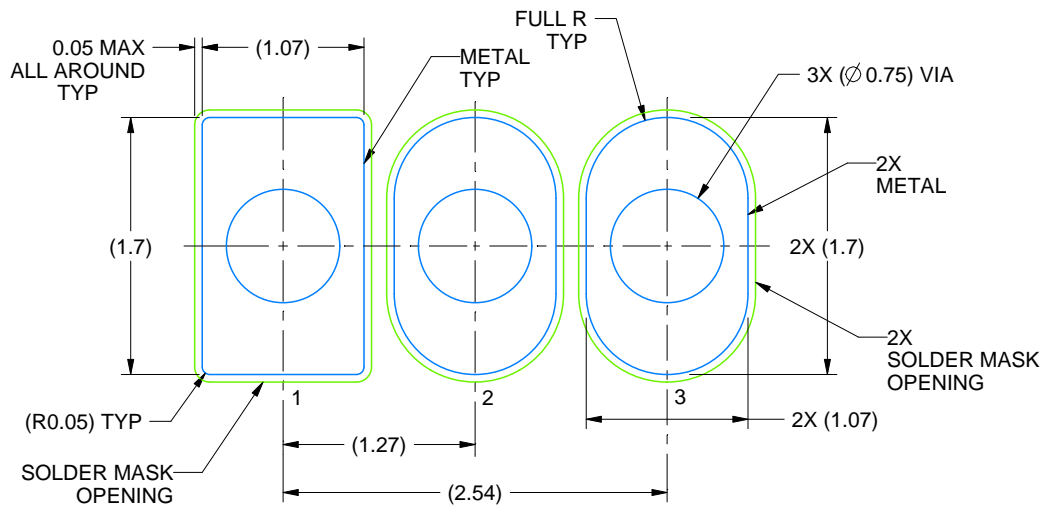
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

LPG0003A

TO-92 - 5.05 mm max height

TRANSISTOR OUTLINE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE:20X

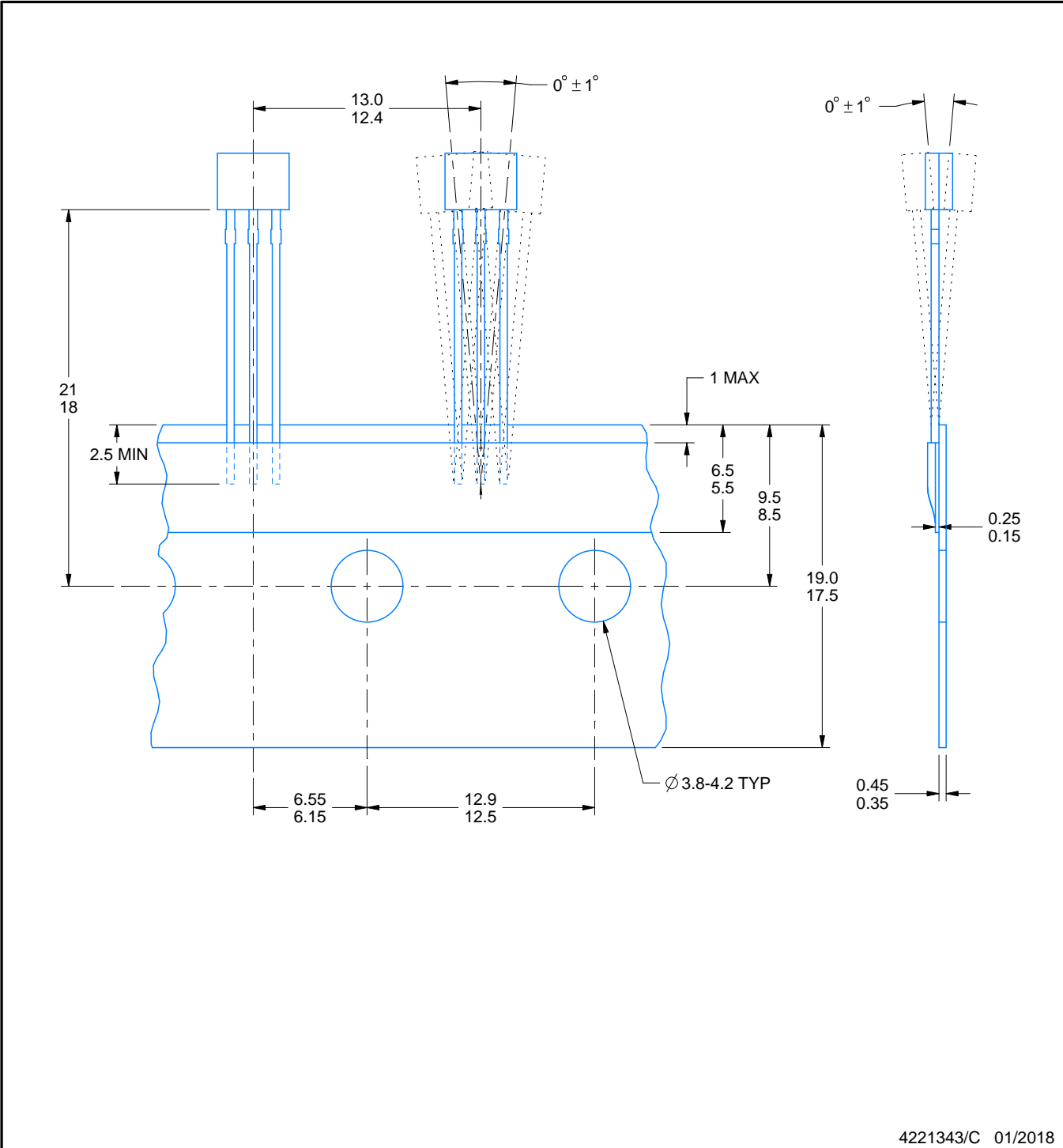
4221343/C 01/2018

TAPE SPECIFICATIONS

LPG0003A

TO-92 - 5.05 mm max height

TRANSISTOR OUTLINE



4221343/C 01/2018

GENERIC PACKAGE VIEW

LP 3

TO-92 - 5.34 mm max height

TRANSISTOR OUTLINE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040001-2/F

LP0003A



PACKAGE OUTLINE

TO-92 - 5.34 mm max height

TO-92



4215214/B 04/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Lead dimensions are not controlled within this area.
4. Reference JEDEC TO-226, variation AA.
5. Shipping method:
 - a. Straight lead option available in bulk pack only.
 - b. Formed lead option available in tape and reel or ammo pack.
 - c. Specific products can be offered in limited combinations of shipping medium and lead options.
 - d. Consult product folder for more information on available options.



LAND PATTERN EXAMPLE
STRAIGHT LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X



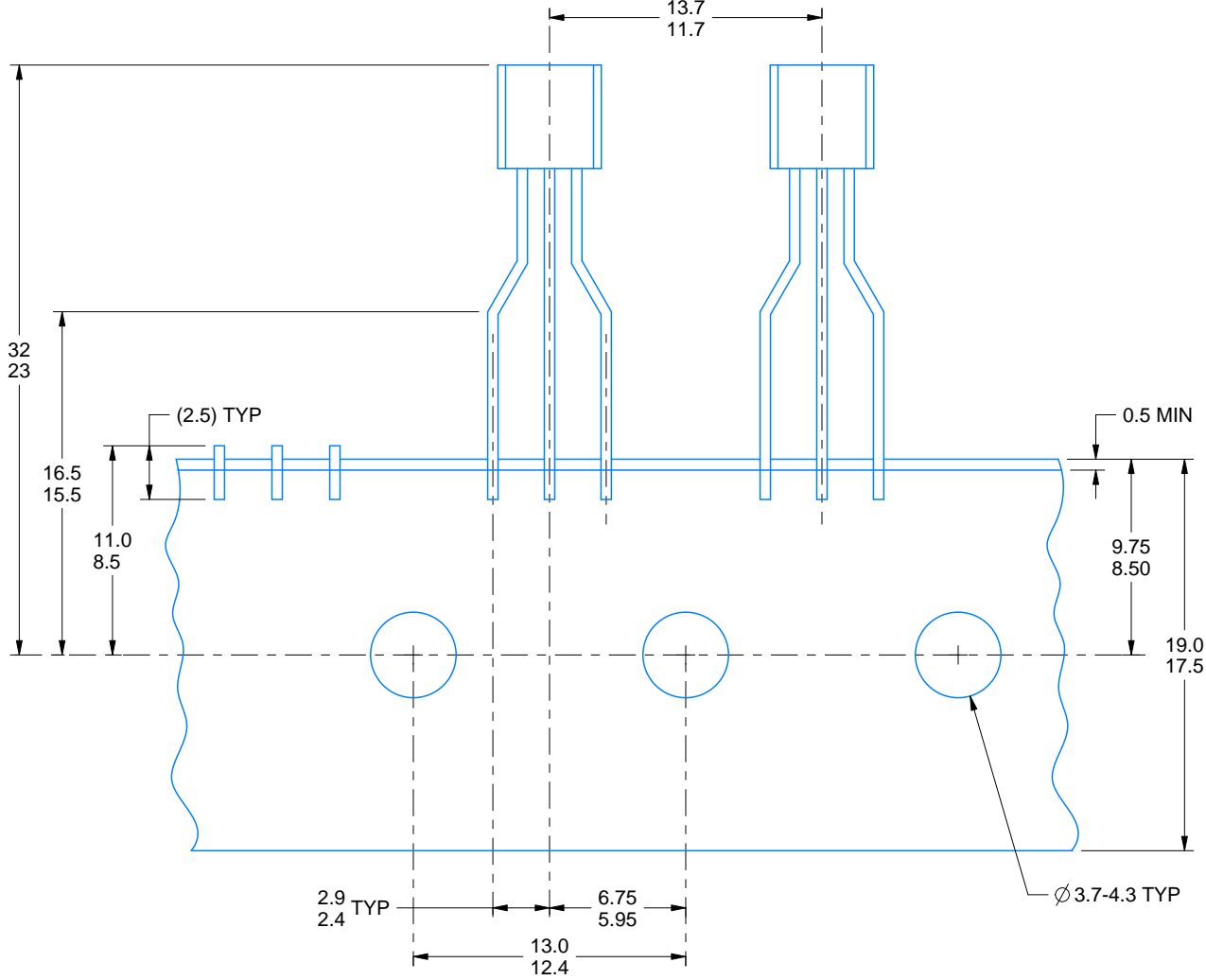
LAND PATTERN EXAMPLE
FORMED LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X

TAPE SPECIFICATIONS

LP0003A

TO-92 - 5.34 mm max height

TO-92

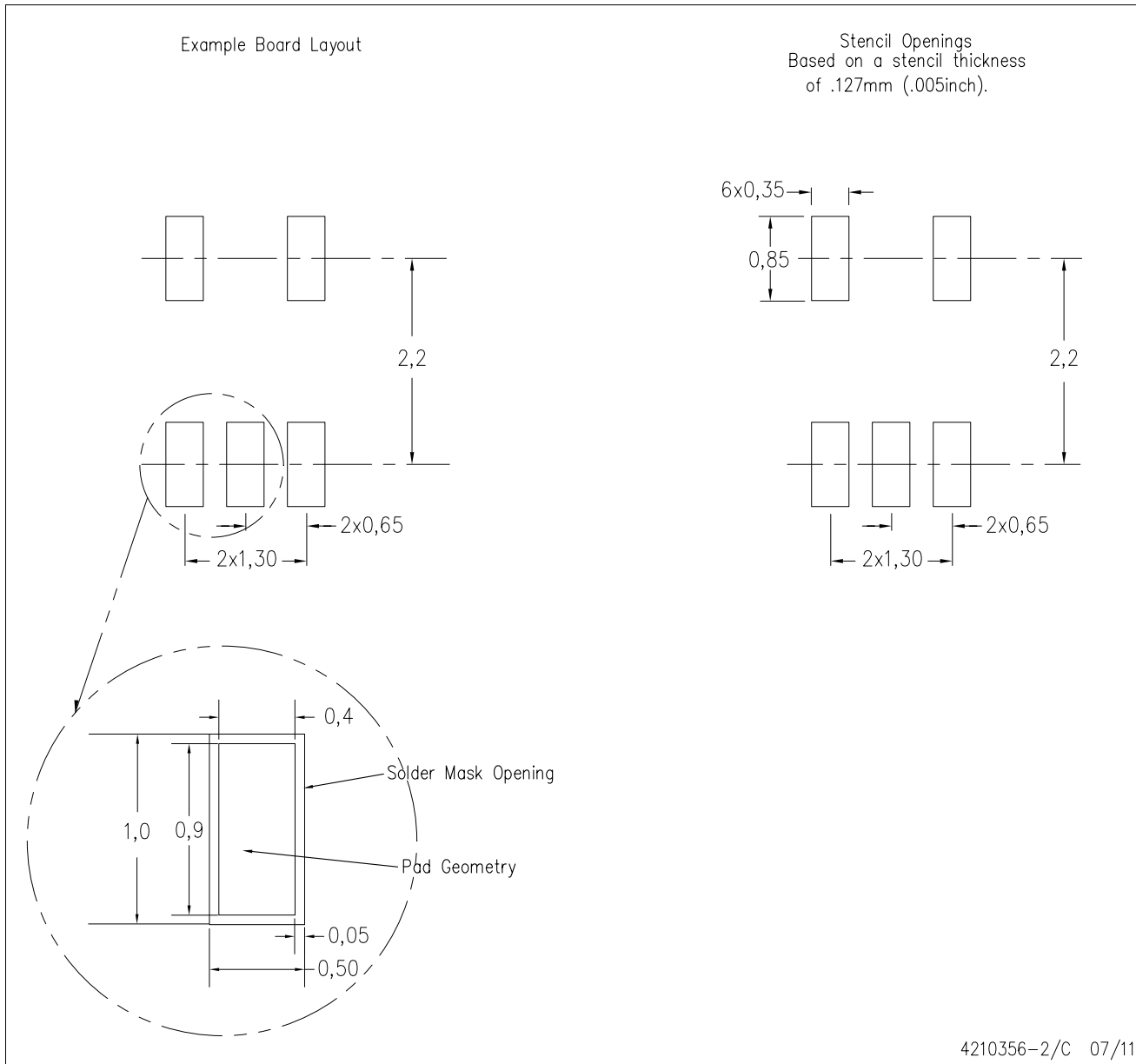


FOR FORMED LEAD OPTION PACKAGE

4215214/B 04/2017

DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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